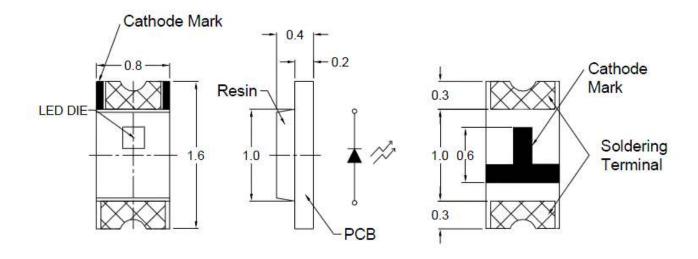
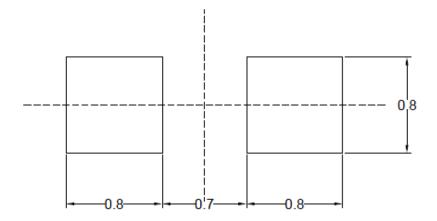


1.6 x 0.8 x 0.4 mm Green SMD LED

PACKAGE OUTLINES



RECOMMENDED PAD LAYOUT



NOTES:

- 1. All dimensions are in millimeters;
- 2. Tolerances are ± 0.2 mm unless otherwise noted.

Part Number	Material	Color		
Part Number		Emitted	Lens	
L196L-MPGC-TR	InGaN/GaN	Green	Water Clear	



1.6 x 0.8 x 0.4 mm Green SMD LED

ABSOLUTE MAXIMUM RATINGS

(Ta=25°C)

Parameter	Symbol	Value	Unit
Forward current	If	20	mA
Reverse current @5V	lr	50	μA
Power dissipation	Pd	80	mW
Peak forward current (1/10 @ 10kHz)	lfp	100	mA
Electrostatic Discharge	ESD	150	V
Operating temperature range	Topr	-40~+85	°C
Storage temperature range	Tstg	-40~+90	°C
Soldering Temperature	Tsol	Max 260°C for 5 sec Max	

OPTICAL-ELECTRICAL CHARACTERISTICS

(Ta=25°C)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Spectral half bandwidth	Δλ	I _F = 20mA		36		nm
Peak Wavelength	λР	I _F = 20mA		518		nm
Dominant wavelength	λD	I _F = 20mA		525		nm
Forward Voltage	Vf	I _F = 20mA		3.5	4.0	V
Luminous intensity	lv	I _F = 20mA	200	500	800	mcd
Viewing angle at 50% lv	20 1/2	I _F = 20mA		140		Deg

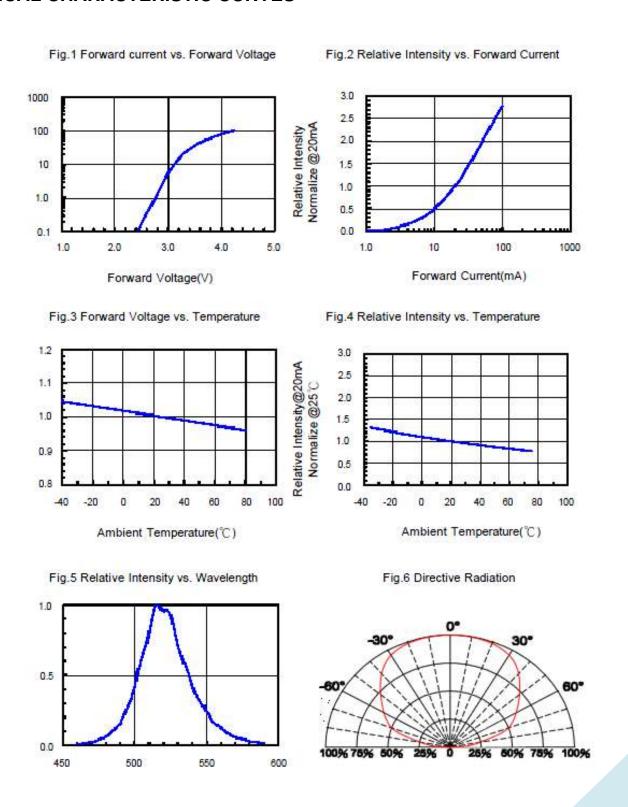
^{*}Note: 1. The forward voltage data did not include ±0.1V testing tolerance.

^{2.} The luminous intensity data did not include ±15% testing balance.



1.6 x 0.8 x 0.4 mm Green SMD LED

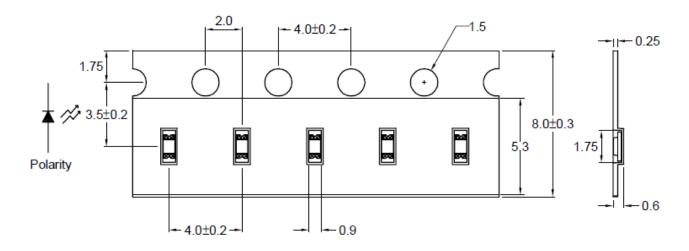
OPTICAL CHARACTERISTIC CURVES





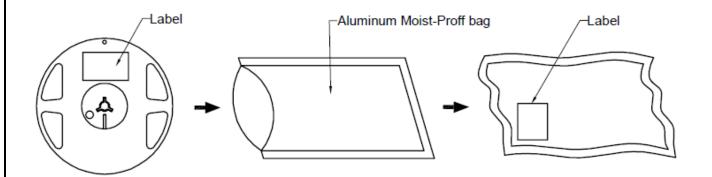
1.6 x 0.8 x 0.4 mm Green SMD LED

CARRIER TYPE DIMENSIONS



Note: The tolerances unless mentioned is ± 0.1 mm, Angle ± 0.5 . Unit=mm.

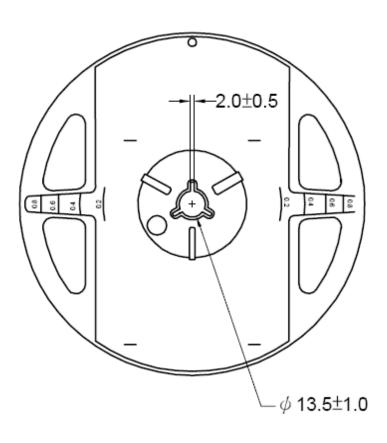
PACKAGING SPECIFICATION

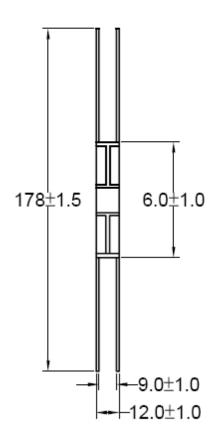




1.6 x 0.8 x 0.4 mm Green SMD LED

REEL DIMENSIONS





Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 4,000pcs/Reel



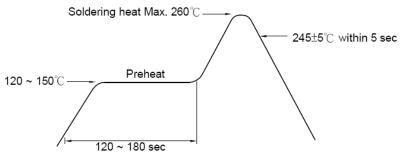
1.6 x 0.8 x 0.4 mm Green SMD LED

RECOMMENDED SOLDERING CONDITIONS

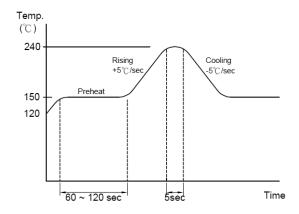
1. Hand Solder

Basic spec is $\leq 280^{\circ}$ C 3 sec one time only.

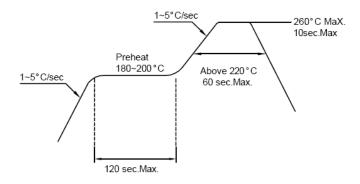
2. Wave Solder



3-1. LEAD Reflow Solder



3-2. PB-Free Reflow Solder



Notes:

- 1. Reflow soldering should not be done more than two times.
- 2. When soldering, do not put stress on the LEDs during heating.
- 3. After soldering, do not warp the circuit board.



1.6 x 0.8 x 0.4 mm Green SMD LED

Precautions for use:

Storage time:

- 1. The operation of temperature and RH are: 5°C~35°C, RH60%.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with descanting agent. Considering the tape life, we suggest our customers to use our products within a year (from production date).
- 3. If opened more than one week in an atmosphere 5° C ~ 35° C, RH60%, they should be treated at 60° C ± 5° C for 15hrs.

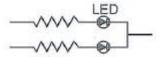
Drive Method:

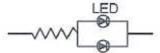
LED is a current operated device, and therefore, require some kind of current limiting incorporated into the driver circuit. This current limiting typically takes the form of a current limiting resistor placed in a series with the LED.

Consider worst case voltage variations that could occur across the current limiting resistor. The forward current should not be allowed to change by more than 40% of its desired value.

Circuit Model A

Circuit Model B





- (A) Recommended circuit.
- (B) The difference of brightness between LED could be found due to the VF-IF characteristics of LED.

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED.

ESD (Electrostatic Discharge):

Static electricity or power surge will damage the LED. Use of a conductive wrist band or antielectrostatic glove is recommended when handling these LED. All devices, equipment and machinery must be properly grounded.



1.6 x 0.8 x 0.4 mm Green SMD LED

Classification	Test Item	Test Conditions	Number of Damaged
Endurance Test	Operating Life Test	1. Ta=under room temperature as per data sheet 2. If=20mA 3. t=1000 hrs (-24hrs, +72hrs)	MIL-STD-750D:1026 MIL-STD-883D: 1005 JIS C 7021: B-1
	High Temperature Storage Test	1. Ta=105°C±5°C 2. t=1000 hrs (-24hrs, +72hrs)	MIL-STD-883D:1008 JIS C 7021: B-10
	Low Temperature Storage Test	1. Ta=40°C±5°C 2. t=1000 hrs (-24hrs, +72hrs)	JIS C 7021: B-12
	High Temperature High Humidity Storage Test	1. Ta=65°C±5°C 2. RH=90%~95% 3. t=1000hrs	MIL-STD-202F:103B JIS C 7021: B-11
Environmental Test	Thermal Shock Test	1. Ta= 105°C±5°C & -40°C±5°C (10min) (10min) 2. Total 10 cycles	MIL-STD-202F: 107D MIL-STD-750D: 1051 MIL-STD-883D: 1011
	Solderability Test	 Tsol=235°C±5°C Immersion time 2±0.5sec Coverage ≥95% of the dipped surface 	MIL-STD-202F: 208D MIL-STD-750D: 2026 MIL-STD-883D: 2003 IEC 68 Part 2-20 JIS C 7021: A-4
	Temperature Cycling	1. 105°C ~ 25°C ~ -55°C ~ 25°C 30 mins 5 mins 30 mins 5 mins 2. 10 cycles	MIL-STD-202F: 107D MIL-STD-750D: 1051 MIL-STD-883D: 1010 JIS C 7021: A-4
	IR Reflow	1. T=260°C Max. 10sec.Max. 2. 6 Min	MIL-STD-750D:2031.2 J-STD-020